

NITTO DENKO AND MICROBONDS FORM ALLIANCE ON MOLDING COMPOUNDS & INSULATED BONDING WIRES

Osaka, JAPAN & Toronto, CANADA, (July 6, 2006) -- Nitto Denko Corporation, a publicly traded Japanese corporation (traded on the Tokyo & Osaka Stock Exchanges, First Section, Code 6988) and Microbonds Inc. (a privately held Canadian corporation) recently announced a co-development project to align the existing products and technology roadmaps for Nitto Denko's leading molding compounds and Microbonds' insulated bonding wire technology, X-Wire™ Technology.

Today's advanced IC designs are pushing the limits of current packaging technologies as the industry continues to decrease geometries and costs, while increasing functionality and interconnect densities. Providing package designers with the flexibility to solve these issues effectively necessitates collaborative development between adjacent packaging processes and technologies. The joint engineering effort to optimize the process windows for Nitto Denko's HC100 & GE100 mold compounds with Microbonds' insulated wire bond technology will provide common customers with validated wire bond and molding parameters for use in advanced IC packages.

Nitto Denko is one of the leading suppliers to the electronics industry, providing a full range of products and integrated technology solutions, including a family of highly engineered molding compounds that are used in many of the most advanced semiconductor packages. "The challenges arising from molding today's longer and thinner bond wires, with closer bond pitches are better addressed by working co-operatively with technologies that impact total cost and yield", said Akihisa Kuroyanagi R&D Manager of Nitto Denko. He further noted, "Microbonds' X-Wire Technology leverages the existing packaging infrastructure and expertise and we are now working with Microbonds to ensure that our customers can use our current mold offerings effectively with insulated wire technology"

William (Bud) Crockett, Director of Business Development for Microbonds noted, "We are honored to be working with Nitto Denko to expand the range and capabilities of insulated bond wire in relation to today's and tomorrows mold compounds while also minimizing the cost and risk of adoption for our common customers. By working co-operatively with adjacent technologies

and processes, insulated bond wire technology will become more robust and users can have more confidence that it is a durable and proven interconnect option.”

About Nitto Denko

Nitto Denko Corporation is a leading global manufacturer and supplier of a wide variety of products and technologies for the electronics Industry with annual sales in excess of US\$6 billion. The Corporation offers a variety of molding resin for semiconductor element packaging that meets the emerging needs for greater speed, greater integration, and various packaging configuration types. Each package comes with completely filled green resin and shows great excellence in outstanding mold ability and reliability. Among others, GE-100 series for BGA/CSP possess top class share in the industry.

Our web site address is www.nitto.com

About Microbonds

Microbonds, Inc. is the leading developer and licensor of insulated wire bonding technologies for use in the design and assembly of microelectronic devices. The company's X-Wire™ Technology has recently received a Technology Innovation Award from SEMI®. The web site address is www.microbonds.com

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